



TOP VIEW
PCB LAYOUT RECOMMENDED

NO.	PART NAME	MATERIAL	STATUS
1	HOUSING	LCP	CODE
2	TERMINAL	Copper Alloy T=0.15	GF/T
3	SHELL	Brass T=0.3	Ni-Plating

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SPECIFICATIONS

Current Rating: 1 Amps
 Insulator Resistance: 100 Megohms min.
 Voltage Rating: 300 VAC
 Operating Temperature: -55°C~+105°C
 IR Reflow Process (Pb Free): Peak Temp-245±5°C
 Conveyor Speed Requirement: 80cm/min (Minimum)
 Housing: High Temperature Thermoplastic
 Contact: Copper Alloy

SBPM 10 F XX T D2 9 C FG
 1 2 3 4 5 6 7 8 9

- Series No.
SBPM=USB 3.0 B Type
- Contact Number:
10=10 Pin
- Contact Type:
F=Female
- Contact Plating:
VF=15u" Gold Plating
5. Solder Tails Area Plating
Selective Plating
T=100u"~200u" Tin
- Apply Type:
D2=Micro Type
- Shell Plating:
9=Tin Plating(Matte)
- Packing Option:
C=Tape & Reel
- Insulator Color:
1=Black
- Environmental:
FG=RoHS(Matte)(Halogen Free)

GENERAL TOLERANCE UNLESS OTHERWISE SPECIFIED	
XXX. ± X	.XX ± 0.10
XX. ± X	.XXX ± X
X. ± 0.50	X.' ± 1"
.X ± 0.30	.X' ± X"



REV. A	DRAWN	09/15/09	SBPM Series
DATE 09/15/09	CHECKED		USB 3.0 Micro B Type - SMT Mount
SCALE As shown	APPROVED		PRODUCT NO. SBPM-10FXXTD29C1-FG
UNIT mm		SIZE A4	FILE NAME SBPM-10FXXTD29C1-FG.DWG